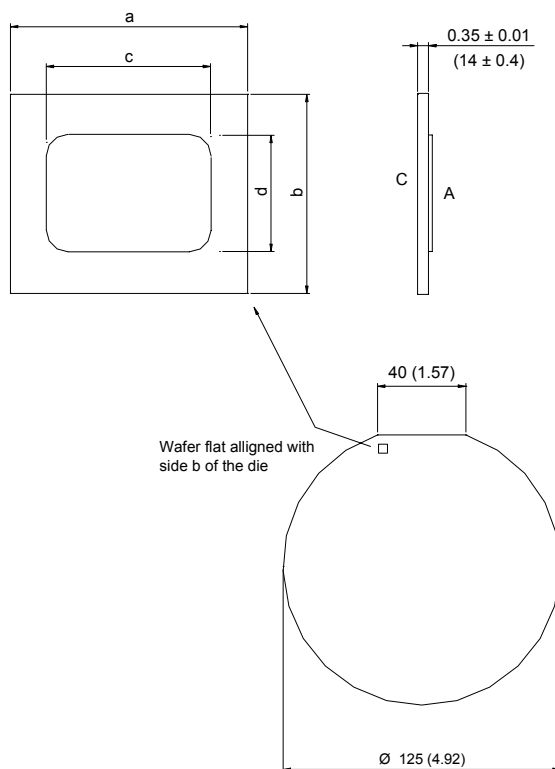




FD060U02A5B

Fred Die in Wafer Form



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION (MILS):

3. DIMENSIONS AND TOLERANCES:

a = 1.524 + 0, -0.01

(60 + 0, -0.4)

b = 1.168 + 0, -0.01

(45.98 + 0, -0.4)

c = 1.310 + 0, -0.01

(51.57 + 0, -0.4)

d = 0.954 + 0, -0.01

(37.56 + 0, -0.4)

4. LETTER DESIGNATION:

A = Anode (Top Metal)

C = Cathode (Back Metal)

5. SAWING:

Recommended Blade

SEMITEC S1025 QS00 Blade

Sawing Street

0.05 + 0, -0.005

(2 + 0, -0.2)

NOT TO SCALE

Reference IR Packaged Part: MURD620CT Series

Electrical Characteristics (Wafer Form)

Parameters	Units	Test Conditions
V_{FM} Maximum Forward Voltage	1.0 V	$T_J = 25^\circ\text{C}$, $I_F = 3\text{ A}$
V_{RRM} Minimum Reverse Breakdown Voltage	200 V	$T_J = 25^\circ\text{C}$, $I_{RRM} = 100\text{ }\mu\text{A}$
I_{RM} Max. Reverse Leakage Current	5 μA	$T_J = 25^\circ\text{C}$, $V_{RRM} = 200\text{ V}$
t_{rr} Typ. Reverse Recovery Time	25 ns	$I_F = 1\text{ A}$, $di_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$

Mechanical Data

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 2 KA - 3 KA)
Nominal Front Metal Composition, Thickness	99% Al, 1% Si (3 microns)
Chip Dimensions	0.060" x 0.046" (see drawing)
Reject Ink Dot Size	0.25 mm diameter minimum
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
FD060xxx5 B	Inked Probed Unsawn Wafer (Wafer in Box)	4800
FD060xxx5 R	Probed Die in Tape & Reel	6000
FD060xxx5 P	Probed Die in Waffle Pack	4800
FD060xxx5 F	Inked Probed Sawn Wafer on Film	4800

Ordering Information Table

Device Code

Digit	Code
1	FD
2	060
3	U
4	02
5	A
6	5
7	B

1	-	Fred Die	
2	-	Chip Dimension in Mils:	060 = 060x046 square
3	-	Process	U = UltraFast
4	-	Voltage code Vrrm (*100) eg:	02 = 200V
5	-	Chip surface metallization:	A = Aluminium (anode), Silver (cathode)
6	-	Wafer diameter in inches	
7	-	Packaging:	B = Inked Probed Unsawn Wafer (Wafer in box)

Data and specifications subject to change without notice.
 This product has been designed and qualified for Industrial Level.
 Qualification Standards can be found on IR's Web site.

International
IR Rectifier

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